



Material Content Data Sheet



Sales Product Name		BSZ900N20NS3 G		Issued		19. July 2018		
MA#		MA000862686						
Package		PG-TSDSON-8-2		Weight*		40.20 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.835	4.56	4.56	45639	45639
leadframe	inorganic material	phosphorus	7723-14-0	0.002	0.01		52	
	non noble metal	zinc	7440-66-6	0.008	0.02		209	
	non noble metal	iron	7439-89-6	0.168	0.42		4170	
wire	non noble metal	copper	7440-50-8	6.808	16.93	17.38	169328	173759
	non noble metal	copper	7440-50-8	0.037	0.09	0.09	929	929
	encapsulation	organic material	carbon black	1333-86-4	0.037	0.09		909
	plastics	epoxy resin	-	1.882	4.68		46821	
	inorganic material	silicondioxide	60676-86-0	16.357	40.71	45.48	406841	454571
leadfinish	non noble metal	tin	7440-31-5	0.387	0.96	0.96	9629	9629
plating	noble metal	silver	7440-22-4	0.963	2.39	2.39	23942	23942
solder	non noble metal	tin	7440-31-5	0.037	0.09		916	
	noble metal	silver	7440-22-4	0.046	0.11		1144	
	non noble metal	lead	7439-92-1	1.758	4.37	4.57	43717	45777
heatspreader	inorganic material	phosphorus	7723-14-0	0.001	0.00		27	
	non noble metal	zinc	7440-66-6	0.004	0.01		107	
	non noble metal	iron	7439-89-6	0.086	0.21		2145	
heat sink CLIP	non noble metal	copper	7440-50-8	3.501	8.71	8.93	87085	89364
	inorganic material	phosphorus	7723-14-0	0.002	0.00		47	
	non noble metal	zinc	7440-66-6	0.008	0.02		188	
	non noble metal	iron	7439-89-6	0.151	0.38		3753	
	non noble metal	copper	7440-50-8	6.127	15.24	15.64	152402	156390
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:
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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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